REMARKS

The specification has been amended to place the application in conformance with standard United States patent practice.

Examination and allowance of pending claims 1-3 are respectfully requested.

Respectfully submitted,

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MARKED-UP AMENDED SPECIFICATION PARAGRAPH

Page 1, title

[PROCESS FOR PRODUCING CARD] CARDS

PROCESS FOR PRODUCING

Page 1, first complete paragraph

The present invention relates generally to a process for producing IC (integrated circuit) cards. More particularly, the present invention relates to a process for producing cards, which can avoid exposure, on the card surface, of unevennesses of components such as IC chips, capacitors and antenna coils mounted or formed on a mount substrate.

Page 4, first section heading

[DISCLOSURE OF THE INVENTION] SUMMARY OF THE INVENTION

Page 6, first section heading

[BRIEF DESCRIPTION OF THE DRAWING] BRIEF DESCRIPTION OF THE DRAWINGS

Page 7, first section heading

[BEST MODE FOR CARRYING OUT THE INVENTION] <u>DETAILED</u>

DESCRIPTION OF THE INVENTION

Page 9, second complete paragraph

Further, an adhesive <u>28, 30</u> in fluid condition [28, 30] is fed over respective surfaces 20A, 22A of the sheet members 20, 22 delivered from the sheet member supply rolls 16, 18 through adhesive supply means 32, 35 such as die coaters or T-dies.

Page 9, third complete paragraph

After the application of the adhesive <u>28, 30</u> in fluid condition [28, 30] over the respective surfaces 20A, 22A of the sheet members 20, 22, the sheet members 20, 22 are guided by means of [a] the pair of guide rolls 24, 26 so that the mount substrate 12 is interposed between the sheet members 20, 22 and so that the spaces defined by both surface sides of the mount substrate 12 and the sheet members 20, 22 are filled with the adhesive 28, 30.